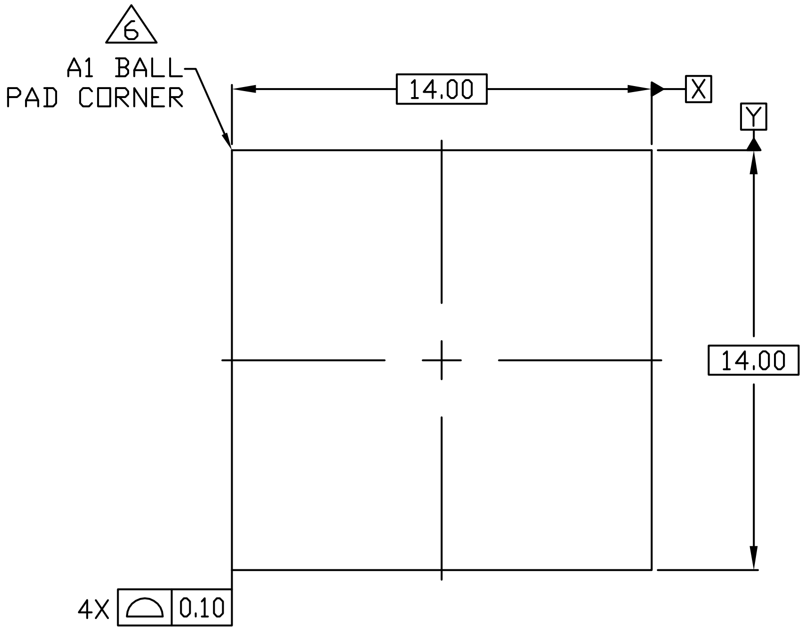
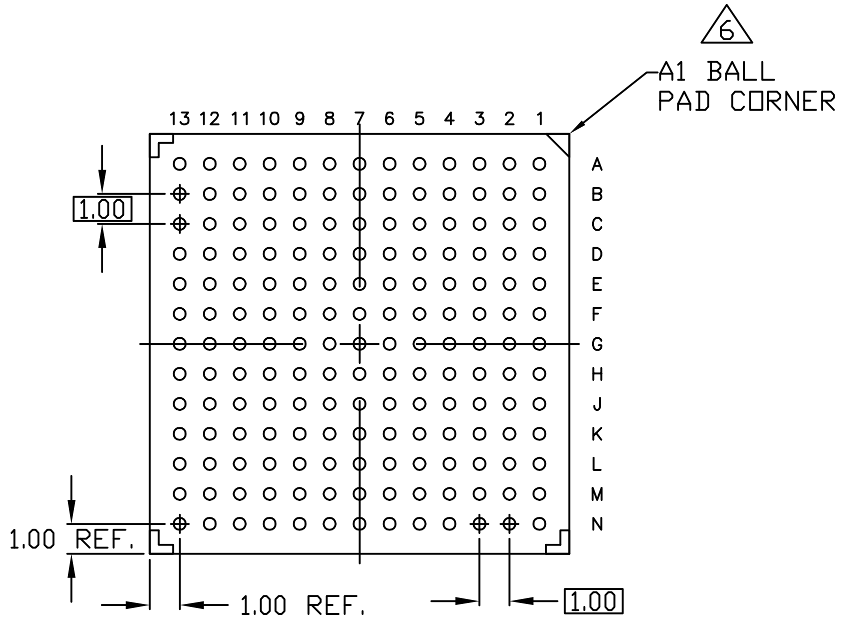
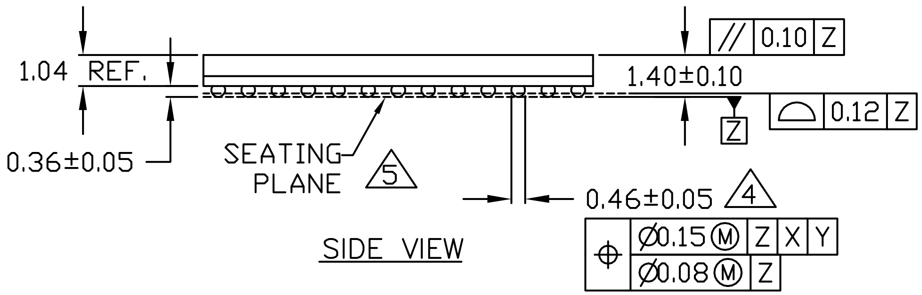


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
5. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND ROHS EXEMPT (#) PKG. CODES.
8. PKG CODE: X169-1

-DRAWING NOT TO SCALE-

TITLE:
PACKAGE OUTLINE, 169 BALLS CSBGA,
14x14mm, 1.00mm PITCH, 2 LAYER

APPROVAL	DOCUMENT CONTROL NO.	REV.	
EDEN CHEN 09/02/10	21-0354	B	1/1